



SANYO Semiconductors

## DATA SHEET

An ON Semiconductor Company

# LV5684PVC — Bi-CMOS LSI

## For Car Audio Systems Multi-Power Supply IC

### Overview

The LV5684PVC is a power supply IC suitable for USB/CD receiver system for car audio system.

This IC integrates 5 systems of regulator output, 2 systems of high side power switch, overcurrent protector, overvoltage protector and overheat protector

Supply for V<sub>DD</sub> and SW33V outputs is low voltage specification, which enables drastic reduction of power dissipation compared to the existing model. (the package is HZIP15J).

### Features

- Low consumption current: 50μA (typ, only V<sub>DD</sub> output is in operation)
- 5 systems of regulator output
  - V<sub>DD</sub> for microcontroller: output voltage: 3.3V, maximum output current: 350mA reverse current protection implemented.
  - For system: output voltage: 3.3V, maximum output current: 450mA
  - For audio: output voltage: 5 to 9V (set by external resistors), maximum output current: 250mA
  - For illumination: output voltage: 5 to 12V (set by external resistors), maximum output current: 300mA
  - For CD: output voltage: 5V/8V, maximum output current: 1300mA
- 2 lines of high side switch with interlock V<sub>CC</sub>
  - EXT: Maximum output current: 350mA, voltage difference between input and output: 0.5V
  - ANT: Maximum output current: 300mA, voltage difference between input and output: 0.5V
- Supply input
  - V<sub>6IN</sub>: 6V for V<sub>DD</sub>, system (SW33V)
  - V<sub>CC1</sub>: For internal reference voltage, control circuits
    - In case of voltage drop of V<sub>6IN</sub>, V<sub>CC1</sub> supplies to V<sub>DD</sub> output.
  - V<sub>CC2</sub>: For AUDIO, illumination, CD, EXT/ANT
- Overcurrent protector
- Overvoltage protector(OVP): V<sub>CC1</sub>, V<sub>CC2</sub> Typ 23V (All outputs except V<sub>DD</sub> are turned off)
- Overvoltage shutdown(OVS): V<sub>6IN</sub> Typ 23V (All outputs except V<sub>DD</sub> are turned off)
- Overheat protector: Typ 175°C

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- PchLDMOS is used in power output block

(Warning) The protector functions only improve the IC's tolerance and they do not guarantee the safety of the IC if used under the conditions out of safety range or ratings. Use of the IC such as use under overcurrent protection range, thermal shutdown state or V6IN OVS condition may degrade the IC's reliability and eventually damage the IC.

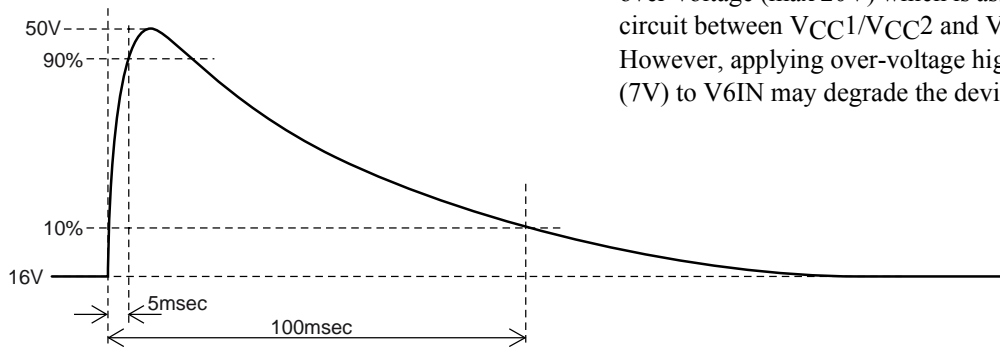
## Specifications

### Absolute Maximum Ratings at Ta = 25°C

Parameter	Conditions	Conditions		Ratings	Unit
Supply voltage	V <sub>CC</sub> max	V <sub>CC</sub> 1, V <sub>CC</sub> 2		36	V
	V <sub>6IN</sub> max	V <sub>6IN</sub> (*)		7	V
Input voltage	V <sub>IN</sub> max	CTRL1, CTRL2		7	V
Allowable power dissipation	Pd max	Independent IC	Ta ≤ 25°C	1.5	W
		Al heat sink *		5.6	W
		With an infinity heat sink		32.5	W
Peak supply voltage	V <sub>CC</sub> peak	See below for the waveform applied.		50	V
Operating ambient temperature	Topr			-40 to +85	°C
Storage temperature	Tstg			-55 to +150	°C
Junction temperature	Tj max			150	°C

\* : When the Aluminum heat sink (50mm × 50mm × 1.5mm) is used

### Waveform of surge test (V<sub>CC1</sub>, V<sub>CC2</sub>)



\*V6IN is designed to tolerant toward short period of over-voltage (max 20V) which is assumed in condition of short circuit between V<sub>CC1</sub>/V<sub>CC2</sub> and V6IN. However, applying over-voltage higher than maximum rating (7V) to V6IN may degrade the device reliability

### Recommended Operating range at Ta = 25°C

#### V<sub>CC1</sub>

Parameter	Conditions	Ratings	Unit
Operating supply voltage 1	V <sub>DD</sub> output	7 to 16	V

#### V<sub>CC2</sub>

Parameter	Conditions	Ratings	Unit
Operating supply voltage 2	ILM output (10V)	12 to 16	V
	ILM output (8V)	10 to 16	V
Operating supply voltage 3	AUDIO output (9V)	10 to 16	V
Operating supply voltage 4	CD output (I <sub>O</sub> = 1.3A)	10.5 to 16	V
	CD output (I <sub>O</sub> ≤ 1A)	10 to 16	V
Operating supply voltage 5	EXT output, ANT output	10 to 16	V

#### V6IN

Parameter	Conditions	Ratings	Unit
Operating supply voltage 6	V <sub>DD</sub> output, SW33V output	5.7 to 6.5	V

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**Electrical Characteristics** at  $V_{CC1} = V_{CC2} = 14.4V$ ,  $V_{6IN} = 6V$  at  $T_a = 25^\circ C$  (\*1)

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Quiescent current	$I_{CC}$	$V_{DD}$ w/out load, CTRL1/2 = "L/L"		50	100	$\mu A$
<b>CTRL1 input (ANT/EXT/ILM)</b>						
Low input voltage	$V_{IL1}$		0		0.5	V
M1 input voltage	$V_{IM11}$		0.8	1.1	1.4	V
M2 input voltage	$V_{IM21}$		1.9	2.2	2.5	V
High input voltage	$V_{IH1}$		2.9	3.3	5.5	V
Input impedance	$R_{IH1}$	input voltage $\leq 3.3V$	280	400	480	$k\Omega$
<b>CTRL2 input (CD/AUDIO/SW33V)</b>						
Low input voltage	$V_{IL2}$		0		0.5	V
M1 input voltage	$V_{IM12}$		0.8	1.1	1.4	V
M2 input voltage	$V_{IM22}$		1.9	2.2	2.5	V
High input voltage	$V_{IH2}$		2.9	3.3	5.5	V
Input impedance	$R_{IH2}$	input voltage $\leq 3.3V$	280	400	480	$k\Omega$
<b><math>V_{DD}</math> output (3.3V) (reverse current prevention diode implemented)</b>						
Output voltage	$V_{O1}$	$I_{O1} = 200mA$	3.13	3.3	3.47	V
Output current	$I_{O1}$	$V_{O1} \geq 3.1V$	350			mA
Line regulation	$\Delta V_{OLN1}$	$5.7V < V_{6IN} < 6.5V$ , $I_{O1} = 200mA$ or $V_{6IN} = 0V$ , $7.5V < V_{CC1} < 16V$ , $I_{O1} = 200mA$		30	90	mV
Load regulation	$\Delta V_{OLD1}$	$1mA < I_{O1} < 200mA$		70	150	mV
Dropout voltage	$V_{DROP1}$	$I_{O1} = 200mA$ , $V_{6IN} = 0V$ (applicable to $V_{CC1}$ )		2.8	3.5	V
Ripple rejection (*2)	$R_{REJ1}$	$f = 120Hz$ , $V_{6IN}$ or $V_{CC1} = 0.5V_{pp}$ $I_{O1} = 200mA$	40	50		dB
Reverse current	$I_{rev}$	$V_{O1} = 3.3V$ , $V_{CC1} = V_{6IN} = 0V$		1	50	$\mu A$
<b>SW33V output (3.3V) ; CTRL2 = "M1 or M2 or H"</b>						
Output voltage	$V_{O2}$	$I_{O2} = 200mA$	3.13	3.3	3.47	V
Output current	$I_{O2}$	$V_{O2} \geq 3.1V$	450			mA
Line regulation	$\Delta V_{OLN2}$	$5.7V < V_{6IN} < 6.5V$ , $I_{O2} = 200mA$		30	90	mV
Load regulation	$\Delta V_{OLD2}$	$1mA < I_{O2} < 200mA$		70	150	mV
Dropout voltage	$V_{DROP2}$	$I_{O2} = 200mA$		0.25	0.5	V
Ripple rejection (*2)	$R_{REJ2}$	$f = 120Hz$ , $V_{6IN}$ or $V_{CC1} = 0.5V_{pp}$ $I_{O2} = 200mA$	40	50		dB
<b>AUDIO (5-9V)output ; CTRL2 = "M1 or M2 or H"</b>						
AUDIO_F voltage	$V_{I3}$		1.212	1.25	1.288	V
AUDIO_F input current	$I_{IN3}$		-1		1	$\mu A$
AUDIO output voltage 1	$V_{O3}$	$I_{O3} = 150mA$ , $R_3 = 30k\Omega$ , $R_4 = 5.6k\Omega$ (*3)	7.65	8.0	8.35	V
AUDIO output voltage 2	$V_{O3'}$	$I_{O3} = 150mA$ , $R_3 = 27k\Omega$ , $R_4 = 4.7k\Omega$ (*3)	8.13	8.5	8.87	V
AUDIO output voltage 3	$V_{O3''}$	$I_{O3} = 150mA$ , $R_3 = 24k\Omega$ , $R_4 = 3.9k\Omega$ (*3)	8.6	9.0	9.4	V
AUDIO output voltage 4	$V_{O3'''}$	$I_{O3} = 150mA$ , $R_3 = 30k\Omega$ , $R_4 = 10k\Omega$ (*3)	4.75	5.0	5.25	V
AUDIO output current	$I_{O3}$		250			mA
Line regulation	$\Delta V_{OLN3}$	$10V < V_{CC2} < 16V$ , $I_{O3} = 150mA$		30	90	mV
Load regulation	$\Delta V_{OLD3}$	$1mA < I_{O3} < 150mA$		70	150	mV
Dropout voltage 1	$V_{DROP3}$	$I_{O3} = 150mA$		0.3	0.45	V
Ripple rejection (*2)	$R_{REJ3}$	$f = 120Hz$ , $I_{O3} = 150mA$	40	50		dB
<b>ILM (5-12V) output ; CTRL1 = "M1 or M2 or H"</b>						
ILM_F voltage	$V_{I4}$		1.212	1.25	1.288	V
ILM_F input current	$I_{IN4}$		-1		1	$\mu A$
ILM output voltage 1	$V_{O4}$	$I_{O4} = 200mA$ , $R_1 = 43k\Omega$ , $R_2 = 5.1k\Omega$ (*3)	11.21	11.8	12.39	V
ILM output voltage 2	$V_{O4'}$	$I_{O4} = 200mA$ , $R_1 = 56k\Omega$ , $R_2 = 7.5k\Omega$ (*3)	9.97	10.5	11.03	V

\*1 : All the specification is defined based on the tests performed under the conditions where  $T_j$  and  $T_a$  ( $= 25^\circ C$ ) are almost equal. These tests were performed with pulse load to minimize the increase of junction temperature ( $T_j$ ).

\*2 : guaranteed by design

\*3 : Using resistors of tolerance within 1%.

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Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
ILM output voltage 3	$V_{O4''}$	$I_{O4} = 200\text{mA}$ , $R1 = 30\text{k}\Omega$ , $R2 = 5.6\text{k}\Omega$ (*3)	7.6	8.0	8.4	V
ILM output voltage 4	$V_{O4'''}$	$I_{O4} = 200\text{mA}$ , $R1 = 30\text{k}\Omega$ , $R2 = 10\text{k}\Omega$ (*3)	4.75	5.0	5.25	V
ILM output current	$I_{O4}$		300			mA
Line regulation	$\Delta V_{OLN4}$	$10\text{V} < V_{CC2} < 16\text{V}$ , $I_{O4} = 200\text{mA}$ $R1 = 30\text{k}\Omega$ , $R2 = 5.6\text{k}\Omega$		30	90	mV
Load regulation	$\Delta V_{OLD4}$	$1\text{mA} < I_{O4} < 200\text{mA}$		70	150	mV
Dropout voltage 1	$V_{DROP4}$	$I_{O4} = 200\text{mA}$		0.7	1.05	V
Dropout voltage 2	$V_{DROP4'}$	$I_{O4} = 100\text{mA}$		0.35	0.53	V
Ripple rejection (*2)	$R_{REJ4}$	$f = 120\text{Hz}$ , $I_{O4} = 200\text{mA}$	40	50		dB
<b>CD (5V/8V output) ; CTRL2 = "H" : 8V, CTRL2 = "M2" : 5V</b>						
Output voltage	$V_{O51}$	$I_{O5} = 1000\text{mA}$	4.75	5.0	5.25	V
	$V_{O52}$	$I_{O5} = 1000\text{mA}$	7.6	8.0	8.4	V
Output current	$I_{O5}$	$V_{O51} \geq 4.7\text{V}$ , $V_{O52} \geq 7.6\text{V}$	1300			mA
Line regulation	$\Delta V_{OLN5}$	$10.5\text{V} < V_{CC2} < 16\text{V}$ , $I_{O5} = 1000\text{mA}$		50	100	mV
Load regulation	$\Delta V_{OLD5}$	$10\text{mA} < I_{O5} < 1000\text{mA}$		100	200	mV
Dropout voltage 1	$V_{DROP5}$	$I_{O5} = 1000\text{mA}$		1.0	1.5	V
Dropout voltage 2	$V_{DROP5'}$	$I_{O5} = 500\text{mA}$		0.5	0.75	V
Ripple rejection (*2)	$R_{REJ5}$	$f = 120\text{Hz}$ , $I_{O5} = 1000\text{mA}$	40	50		dB
<b>EXT_HS-SW ; CTRL1 = "M2 or H"</b>						
Output voltage	$V_{O6}$	$I_{O6} = 350\text{mA}$	$V_{CC2}-1.0$	$V_{CC2}-0.5$		V
Output current	$I_{O6}$	$V_{O6} \geq V_{CC2}-1.0$	350			mA
<b>ANT_HS-SW ; CTRL1 = "H"</b>						
Output voltage	$V_{O7}$	$I_{O7} = 300\text{mA}$	$V_{CC2}-1.0$	$V_{CC2}-0.5$		V
Output current	$I_{O7}$	$V_{O7} \geq V_{CC2}-1.0$	300			mA

\*2 : guaranteed by design

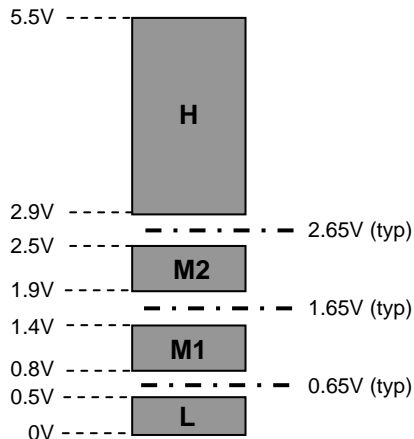
\*3 : Using resistors of tolerance within 1%.

## CTRL logic truth table

CTRL1	ANT	EXT	ILM
H	ON	ON	ON
M2	OFF	ON	ON
M1	OFF	OFF	ON
L	OFF	OFF	OFF

CTRL2	CD	AUDIO	SW33V
H	ON (8V)	ON	ON
M2	ON (5V)	ON	ON
M1	OFF	ON	ON
L	OFF	OFF	OFF

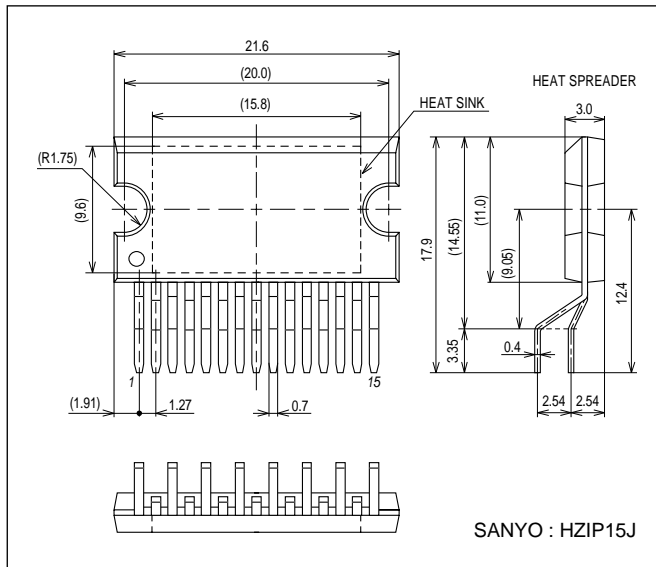
## CTRL1/2 voltage range and threshold



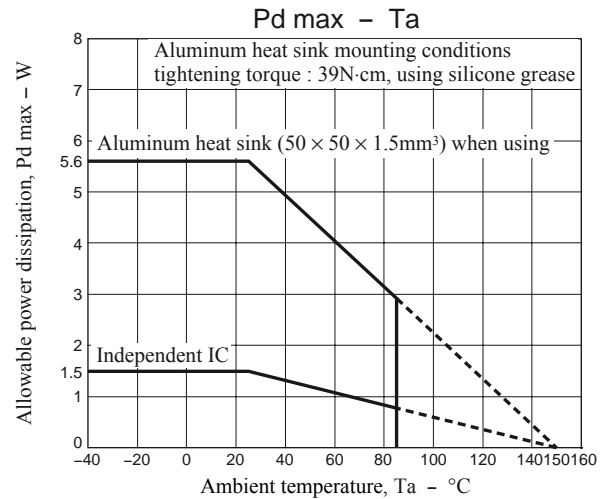
# LV5684PVC

## Package Dimensions

unit : mm (typ)  
3395

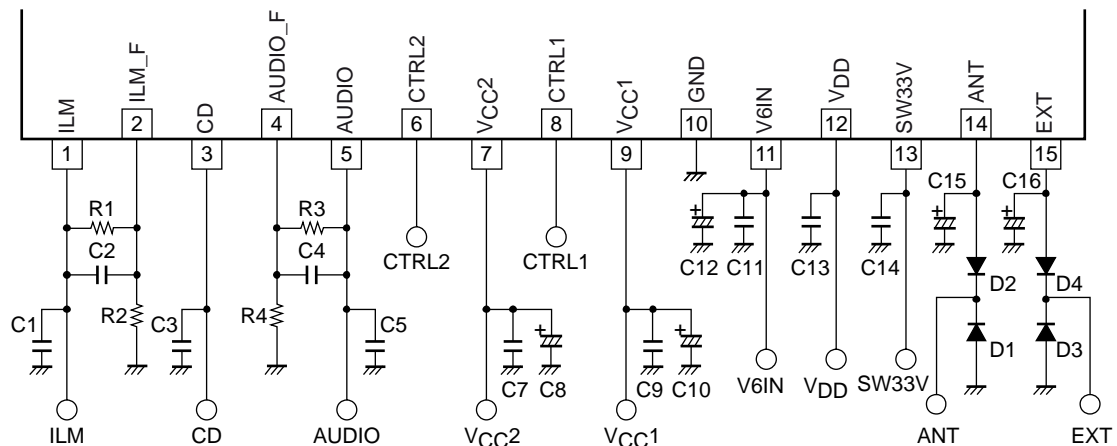


- Allowable power dissipation derating curve



## Application Circuit Example

### LV5684PVC

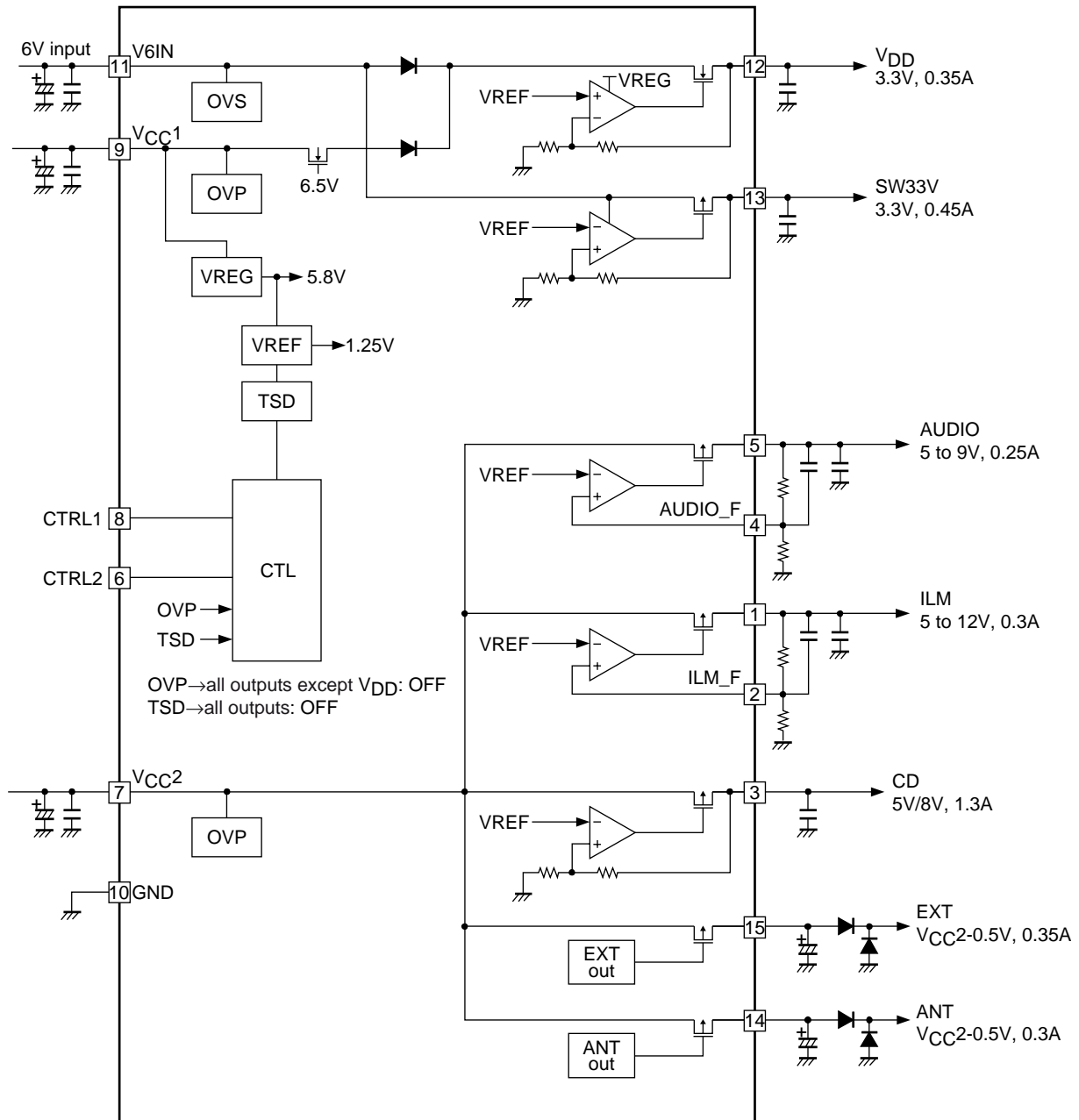


## Peripheral parts

Part name	Description	Recommended value	Note
C1, C3, C5, C13, C14	output stabilization capacitor	greater than 10μF (*1)	
C2, C4	output stabilization capacitor	0pF	Ceramic capacitor
C8, C10, C12	Capacitor for bypass power supply	C8: greater than 100μF C10, C12: greater than 47μF	Make sure to implement close to V <sub>CC</sub> and GND.
C7, C9, C11	Capacitor for oscillation protector	greater than 0.22μF	
C15, C16	Capacitor for EXT/ANT output stabilization	greater than 2.2μF	
R1, R2	ILM voltage setting	R1/R2 43kΩ/5.1kΩ : V <sub>O</sub> = 12V 56kΩ/7.5kΩ : V <sub>O</sub> = 10.5V 30kΩ/5.6kΩ : V <sub>O</sub> = 8V 30kΩ/10kΩ : V <sub>O</sub> = 5V	Use resistors of tolerance within 1%
R3, R4	AUDIO voltage setting	R3/R4 30kΩ/10kΩ : V <sub>O</sub> = 5V 30kΩ/5.6kΩ : V <sub>O</sub> = 8.0V 27kΩ/4.7kΩ : V <sub>O</sub> = 8.5V 24kΩ/3.9kΩ : V <sub>O</sub> = 9V	Use resistors of tolerance within 1%
D1, D2, D3, D4	Internal device protector diode	SANYO SB1003M3	

(\*1) Make sure that output capacitors are greater than 10uF and meets the condition of ESR = 0.001 to 10Ω , in which voltage/ temperature dependence and unit differences are taken into consideration. Moreover, in case of electrolytic capacitor, high-frequency characteristics should be sufficiently good.

## Block Diagram



## Pin Function

Pin No.	Pin name	Description	Equivalent Circuit
1	ILM	ILM output When CTRL1 = M1, M2, H, ILM is ON	
2	ILM_F	ILM voltage adjust	

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Pin No.	Pin name	Description	Equivalent Circuit
3	CD	CD output When CTRL2 = M2, H, CD is ON 5V or 8V/1.3A	
4	AUDIO_F	AUDIO voltage adjust	
5	AUDIO	AUDIO output When CTRL2 = M1, M2, H, AUDIO is ON	
6	CTRL2	CTRL2 input 4-value input	
7	VCC2	Power supply	
8	CTRL1	CTRL1 input 4-value input	
9	VCC1	Power supply	
10	GND	GND	
11	V6IN	Power supply	

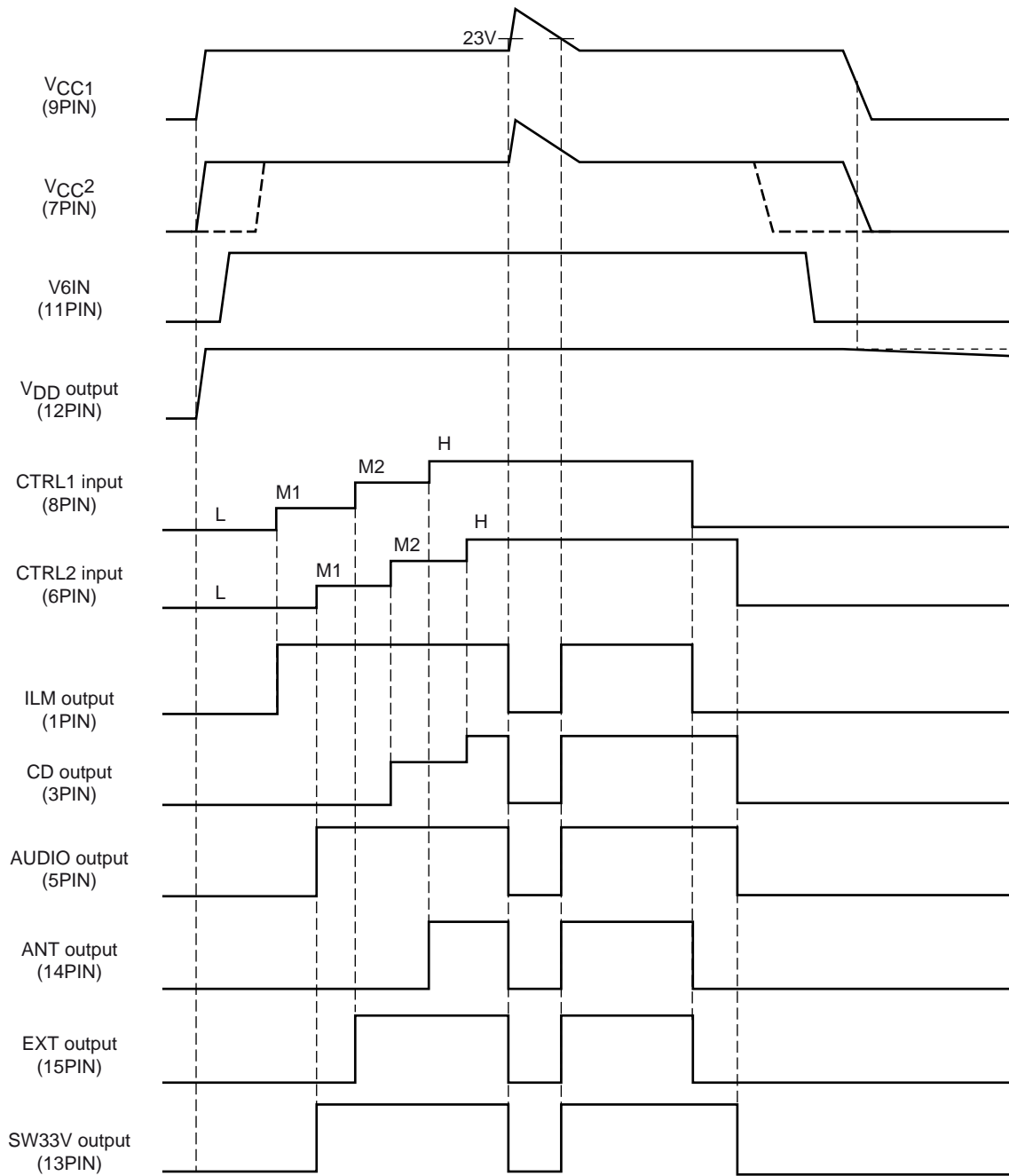
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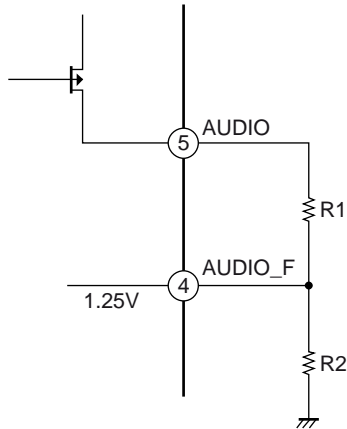
Pin No.	Pin name	Description	Equivalent Circuit
12	V <sub>DD</sub>	V <sub>DD</sub> output 3.3V/0.35A	
13	SW33V	SW33V output When CTRL2 = M1, M2, H, SW33V is ON 3.3V/0.45A	
14	ANT	ANT output When CTRL1 = H, ANT is ON V <sub>CC</sub> -0.5V/300mA	
15	EXT	EXT output When CTRL1 = M2, H, EXT is ON V <sub>CC</sub> -0.5V/350mA	

# Timing Chart



Caution: The above values are obtained when typ.

- How to set AUDIO output voltage



[ AUDIO\_F is determined by internal band-gap reference voltage (typ = 1.25V). ]

AUDIO output voltage expression

$$AUDIO = \left( \frac{R_1}{R_2} + 1 \right) \times 1.25[V]$$

$$\frac{R_1}{R_2} = \frac{AUDIO}{1.25} - 1$$

Set the ratio of R1 and R2 to satisfy above expression.

(ex) AUDIO = 9V setting

$$\frac{R_1}{R_2} = \frac{9}{1.25} - 1 = 6.2$$

$$\frac{R_1}{R_2} = \frac{24k\Omega}{3.9k\Omega} \cong 6.15$$

$$AUDIO = (6.15 + 1) \times 1.25V \cong 8.94V$$

- ILM output voltage is similarly calculated as AUDIO output.

(ex) ILM = 10.5V setting

$$\frac{R_1}{R_2} = \frac{10.5}{1.25} - 1 = 7.4$$

$$\frac{R_1}{R_2} = \frac{56k\Omega}{7.5k\Omega} \cong 7.46$$

$$ILM = (7.46 + 1) \times 1.25V \cong 10.575V$$

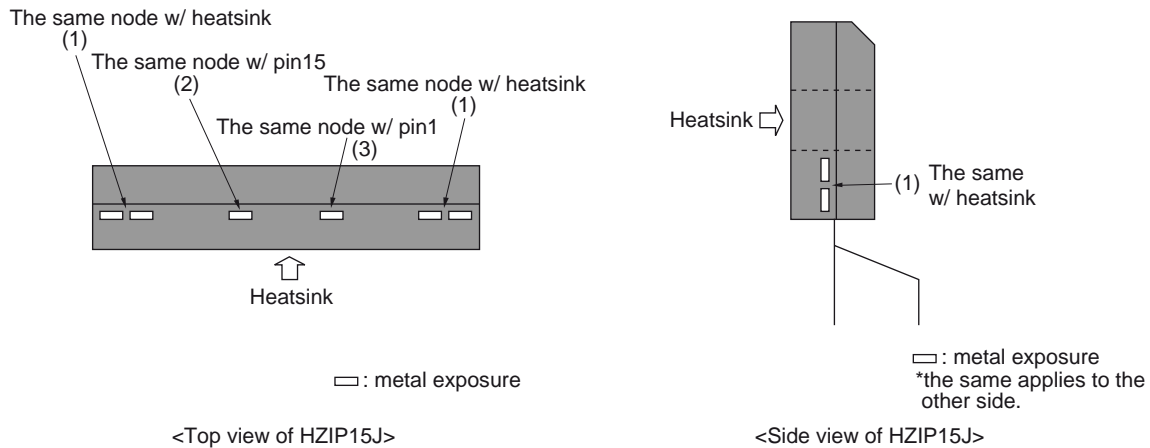
Note : The above values are typical values. These values have variation among the range of their tolerances.

## LV5684PVC

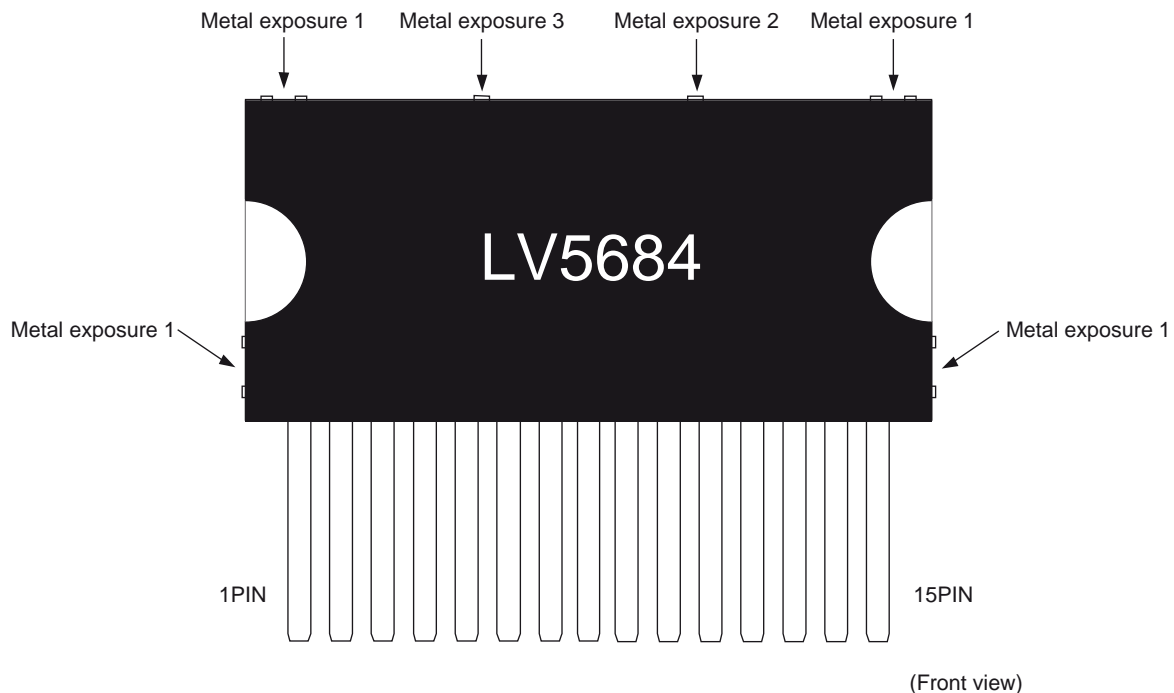
### Warning: Implementing LV5684PVC to the set board

The package of LV5684PVC is HZIP15J which has some metal exposures other than connection pins and heatsink as shown in the diagram below. The electrical potentials of (2) and (3) are the same as those of pin15 and pin1, respectively. (2) (= pin15) is the EXT (High-side switch) output pin and (3) (= pin1) is the ILM (regulator) output pin. When you implement the IC to the set board, make sure that the bolts and the heatsink are out of touch from (2) and (3). If the metal exposures touch the bolts which has the same electrical potential with GND, GND short occurs in ILM output and EXT output. The exposures of (1) are connected to heatsink which has the same electrical potential with substrate of the IC chip (GND). Therefore, (1) and GND electrical potential of the set board can contact each other.

### HZIP15J outline



### Frame diagram (HZIP15J)



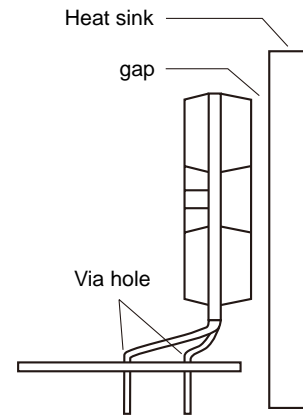
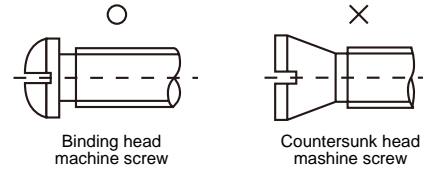
**HZIP15J Heat sink attachment**

Heat sinks are used to lower the semiconductor device junction temperature by leading the heat generated by the device to the outer environment and dissipating that heat.

- a. Unless otherwise specified, for power ICs with tabs and power ICs with attached heat sinks, solder must not be applied to the heat sink or tabs.

b. Heat sink attachment

- Use flat-head screws to attach heat sinks.
  - Use also washer to protect the package.
  - Use tightening torques in the ranges 39-59Ncm (4-6kgcm) .
  - If tapping screws are used, do not use screws with a diameter larger than the holes in the semiconductor device itself.
  - Do not make gap, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
  - Take care a position of via hole .
  - Do not allow dirt, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
  - Verify that there are no press burrs or screw-hole burrs on the heat sink.
  - Warping in heat sinks and printed circuit boards must be no more than 0.05 mm between screw holes, for either concave or convex warping.
  - Twisting must be limited to under 0.05 mm.
  - Heat sink and semiconductor device are mounted in parallel.
- Take care of electric or compressed air drivers
- The speed of these torque wrenches should never exceed 700 rpm, and should typically be about 400 rpm.



c. Silicone grease

- Spread the silicone grease evenly when mounting heat sinks.
- Sanyo recommends YG-6260 (Momentive Performance Materials Japan LLC)

d. Mount

- First mount the heat sink on the semiconductor device, and then mount that assembly on the printed circuit board.
- When attaching a heat sink after mounting a semiconductor device into the printed circuit board, when tightening up a heat sink with the screw, the mechanical stress which is impossible to the semiconductor device and the pin doesn't hang.

e. When mounting the semiconductor device to the heat sink using jigs, etc.,

- Take care not to allow the device to ride onto the jig or positioning dowel.
- Design the jig so that no unreasonable mechanical stress is applied to the semiconductor device.

f. Heat sink screw holes

- Be sure that chamfering and shear drop of heat sinks must not be larger than the diameter of screw head used.
- When using nuts, do not make the heat sink hole diameters larger than the diameter of the head of the screws used. A hole diameter about 15% larger than the diameter of the screw is desirable.
- When tap screws are used, be sure that the diameter of the holes in the heat sink are not too small. A diameter about 15% smaller than the diameter of the screw is desirable.

- g. There is a method to mount the semiconductor device to the heat sink by using a spring band. But this method is not recommended because of possible displacement due to fluctuation of the spring force with time or vibration.

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